

KNOWN GOOD DIE: In an Era of Multi-Die Packaging and 3D Integration 2011

**Santa Clara, California, USA
10 November 2011**

ISBN: 978-1-61839-449-1

Printed from e-media with permission by:

Curran Associates, Inc.
57 Morehouse Lane
Red Hook, NY 12571



Some format issues inherent in the e-media version may also appear in this print version.

Copyright© (2011) by MEPTEC
All rights reserved.

Printed by Curran Associates, Inc. (2012)

For permission requests, please contact MEPTEC
at the address below.

MEPTEC
P.O. Box 222
Medicine Park, Oklahoma 73557

Phone: 650-714-1570
Fax: 1-866-424-0130

info@meptec.org

Additional copies of this publication are available from:

Curran Associates, Inc.
57 Morehouse Lane
Red Hook, NY 12571 USA
Phone: 845-758-0400
Fax: 845-758-2634
Email: curran@proceedings.com
Web: www.proceedings.com

KNOWN GOOD DIE IN AN ERA OF MULTI-DIE PACKAGING AND 3D INTEGRATION

CONTENTS

Agenda

Sponsor and Exhibitor Directory

Participant Biographies

SESSION ONE: CURRENT AND FUTURE BARE DIE ISSUES

- **Integrating Multi-Die: The Infrastructure Complexity**%
Ron Leckie, INFRASTRUCTURE Advisors
- **Mitigating the Impact of Counterfeit Components and KGD**B#5
David Looney, Premier Semiconductor Services LLC
- **3DIC Total Yield Assurance**&%
Nevo Laron, Camtek USA

SESSION TWO: KGD TEST - HOW GOOD IS GOOD ENOUGH?

- **KGD Probing Strategies for Through-Silicon Stacking**) &
Ken Smith, Cascade Microtech, Inc.
- **Optimizing the Cost of Test for Multi-die Systems in Packaging (SIP)**+-
Omer Dossani, STATS ChipPAC
- **L]]bl 'G]dgK cf Xfg <][\Ygh7UdW]m: D; 5'UbX'G'UHyfg'±Xi gfmFYWfX Zcf Bi a VYf'cZHfUbg]ghcf gVm&L - %**
Jae Cho, Xilinx, Inc.

KEYNOTE:

- **KGD is Cool Again**%\$-
Ivor Barber, LSI Corporation

SESSION THREE: KGD INFRASTRUCTURE

- **Small Footprint Stacked Die Package and HVM Supply Chain Readiness**%&%
Marc Robinson, Vertical Circuits, Inc.
- **What If ... There Was a KGD Standards Committee?**%) (
Steve Steps, Aehr Test Systems
- **How Well Known is Your Good Die?**%+ '
Jeremy Adams, Micross Components

SESSION FOUR: PANEL - A GOOD DIE IS HARD TO FIND

Moderator:%)
Linda Matthew, TechSearch International, Inc.

Panelists:% +
Stephanie Althouse, Ph.D., NxGEN Electronics
Adam Cron, Synopsys, Inc.
Dave Love, Oracle Corporation
Phil Marcoux, PPM Associates
Manish Ranjan, Ultratech Inc.